

FORESEE eMMC FEMDNN064G-58K72 Datasheet

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Revision History:

Rev.	Date	Changes	Remark
1.0	2020/03/25	Basic spec and architecture	Target

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1. Introduction

FORESEE eMMC is an embedded storage solution designed in the BGA package. The FORESEE eMMC consists of NAND flash and eMMC controller. The controller could manage the interface protocols, wear-leveling, bad block management and ECC.

FORESEE eMMC has high performance at a competitive cost, high quality and low power consumption, and eMMC is compatible with JEDEC standard eMMC 5.1 specifications.

2. Product List

Density	Part Number	Capacity (User Density)	Package Size(mm)	Package Type
64GB	FEMDNN064G-58K72	57.6GB	11.5x13x1.0	153 FBGA

3. Features

- **eMMC5.1 specification compatibility**
(Backward compatible to eMMC4.41/4.5/5.0)
- **Bus mode**
 - Data bus width: 1 bit (default), 4 bits, 8 bits
 - Data transfer rate: up to 400MB/s (HS400)
 - MMC I/F Clock frequency : 0~200MHz
- **Operating voltage range**
 - Vcc(NAND) : 2.7 - 3.6V
 - Vccq(Controller) : 1.7 - 1.95V / 2.7 - 3.6V
- **Temperature**
 - Operation (-25°C ~ +85°C)
 - Storage without operation (-40°C ~ +85°C)
- **Sudden-Power-Loss safeguard**
- **Hardware ECC engine**
- **Unique firmware backup mechanism**
- **Global-wear-leveling**
- **Supported features.**
 - HS400, HS200
 - Partitioning, RPMB
 - Boot feature, boot partition
 - HW Reset/SW Reset
 - Discard, Trim, Erase, Sanitize
 - Background operations, HPI
 - Enhanced reliable write
 - S.M.A.R.T. Health Report
 - FFU
 - Sleep / awake
- **Others**
 - Compliance with the RoHS Directive

4. Functional Description

FORESEE eMMC with powerful L2P (Logical to Physical) NAND Flash management algorithm provides unique functions:

- Host independence from details of operating NAND flash
- Internal ECC to correct defect in NAND flash
- Sudden-Power-Loss safeguard
To prevent from data loss, a mechanism named Sudden-Power-Loss safeguard is added in the eMMC. In the case of sudden power-failure, the eMMC would work properly after power cycling.
- Global-wear-leveling
To achieve the best stability and device endurance, this eMMC equips the Global Wear Leveling algorithm. It ensures that not only normal area, but also the frequently accessed area, such as FAT, would be programmed and erased evenly.
- IDA(Initial Data Acceleration)
The eMMC prevents the pre-burned data from data-loss with IDA, in case of our customer had pre-burned data to eMMC, before the eMMC being SMT.
- Cache
The eMMC enhanced the data written performance with Cache, with which our customer would get more endurance and reliability.

5. Product Specifications

5.1 Performance

Density	Write	Read
64GB	Up to 100MB/s	Up to 230 MB/s

- Test Condition: Bus width x8, 200MHz DDR, 512KB data transfer, w/o file system overhead, measured on internal board
- Test tool: CMD
- Test area: 1GB/ Full-range of LBA.

5.2 Power Consumption

5.2.1 Active power consumption during operation

Density	Icc	Iccq
64GB	120mA	120mA

- Power Measurement conditions: Bus configuration =x8 @200MHz DDR, 25°C.
- Vcc:3.3V & Vccq: 1.8V.
- The measurement for max RMS current is the average RMS current consumption over a period of 100ms.

5.2.2 Low power mode (stand-by)

Density	Icc	Iccq
64GB	160uA	160uA

- Power Measurement conditions: Bus configuration =x8 @200MHz DDR, 25°C.
- Vcc:3.3V & Vccq: 1.8V.
- Standby: Nand Vcc & Controller Vccq power supply is switched on.
- The measurement for max RMS current is the average RMS current consumption over a period of 100ms.

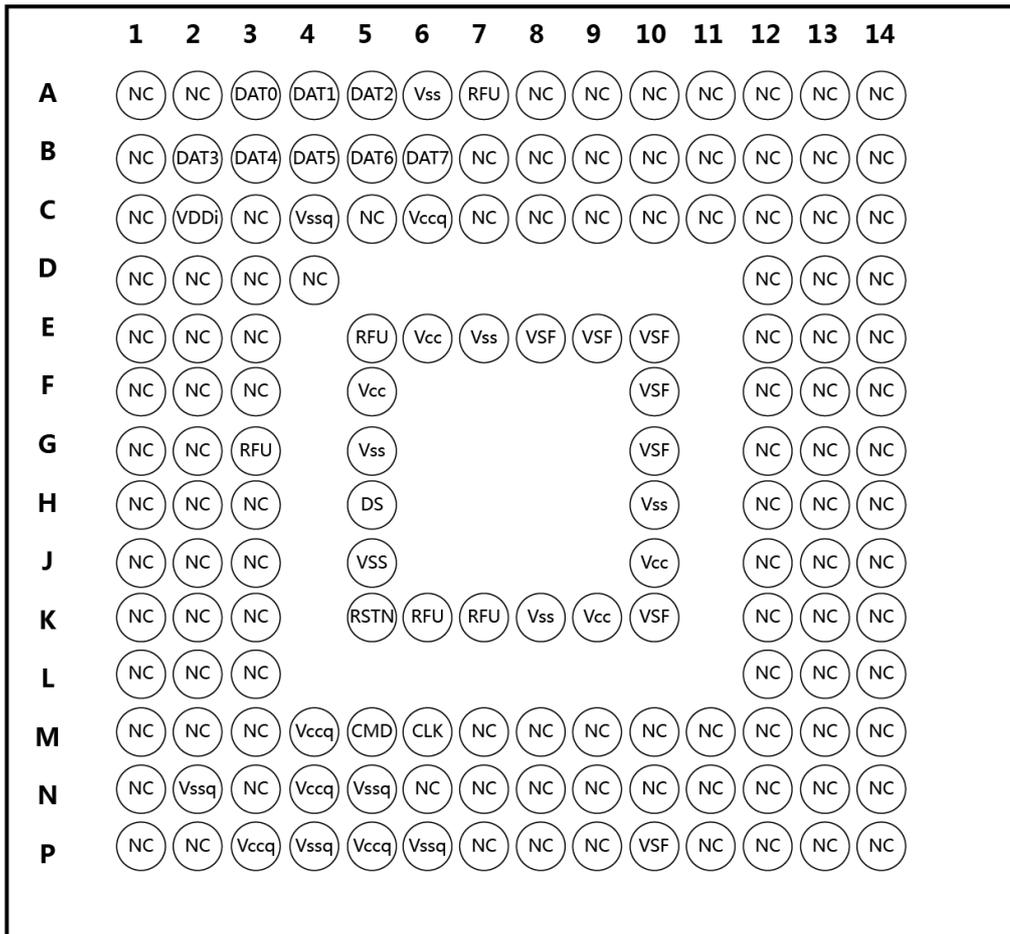
5.2.3 Low power mode (sleep)

Density	Icc	Iccq
64GB	0	100uA

- Power Measurement conditions: Bus configuration =x8 @200MHz DDR, 25°C.
- Vcc:3.3V & Vccq: 1.8V.
- Sleep: Nand Vcc power supply is switched off(Controller Vccq on)
- The measurement for max RMS current is the average RMS current consumption over a period of 100ms.

6. Pin Assignments

6.1 Ball Array view



FBGA153 - Ball Array (Top View through package)

6.2 Ball Array view

Signal	Description
CLOCK (CLK)	Each cycle of the clock directs a transfer on the command line and on the data lines.
COMMAND (CMD)	This signal is a bidirectional command channel used for device initialization and command transfer. The CMD Signal has 2 operation modes: open drain, for initialization, and push-pull, for command transfer. Commands are sent from the host to the device, and responses are sent from the device to the host.
DATA (DAT0-DAT7)	These are bidirectional data signal. The DAT signals operate in push-pull mode. By default, after power-up or RESET, only DAT0 is used for data transfer. The controller can configure a wider data bus for data transfer wither using DAT [3:0](4bit mode)or DAT[7:0](8bit mode). Includes internal pull-up resistors for data lines DAT[7:1].Immediately after entering the 4-bit mode, the device disconnects the internal pull-up resistors on the DAT1 and DAT2 lines.(The DAT3 line internal pull-up is left connected.)Upon entering the 8bit mode, the device disconnects the internal pull-up on the DAT1, DAT2, and DAT[7:4]lines.
Data Strobe (DS)	Newly assigned pin for HS400 mode. Data Strobe is generated from e.MMC to host. In HS400 mode, read data and CRC response are synchronized with Data Strobe.
RESET (RSTN)	Hardware Reset Input
Vccq	Vccq is the power supply line for host interface, have two power mode: High power mode:2.7V~3.6V; Lower power mode:1.7V~1.95V
Vcc	Vcc is the power supply line for internal flash memory, its power voltage range is:2.7V~3.6V
VDDi	VDDi is internal power node, not the power supply. Connect 1uF capacitor VDDi to ground
Vss,Vssq	Ground lines.

Note:

NC: No Connect, shall be connected to ground or left floating.

RFU: Reserved for Future Use, must be left floating for future use.

VSF: Vendor Specific Function, must be left floating.